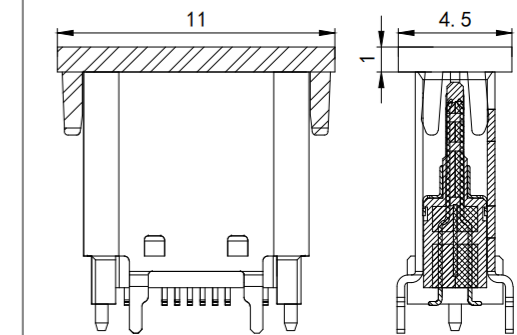
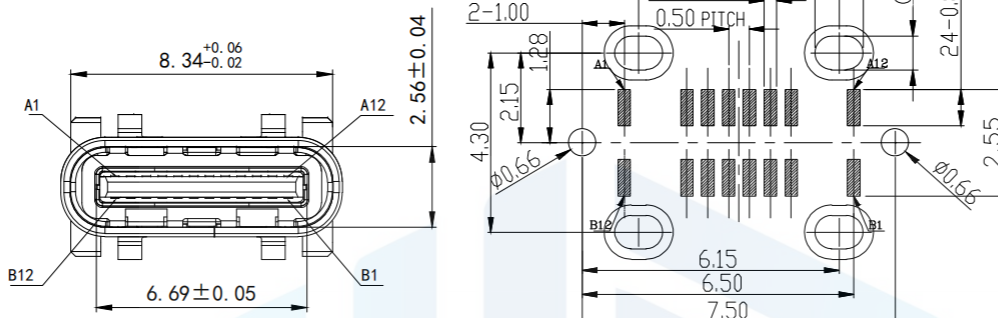
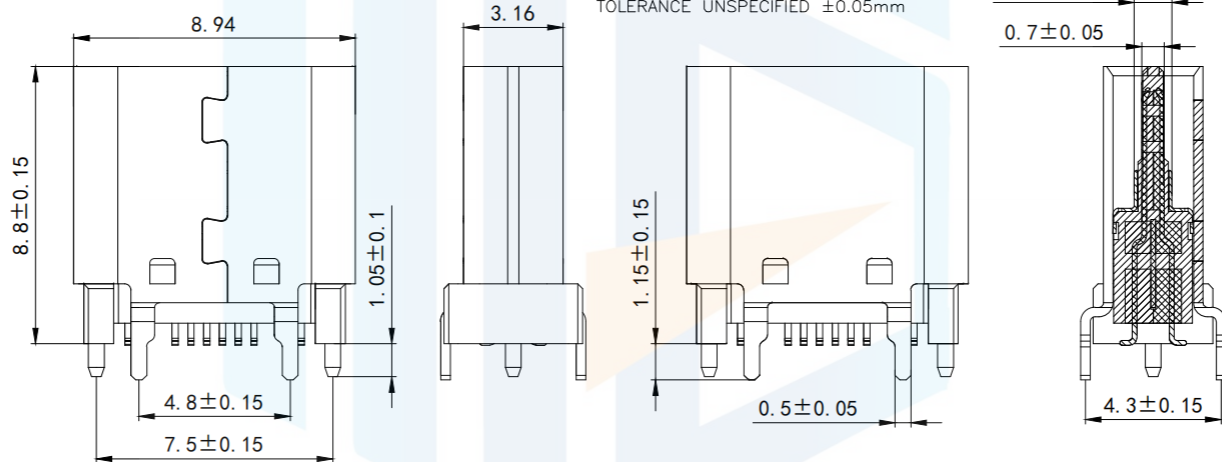


RoHS2.0
Compliant



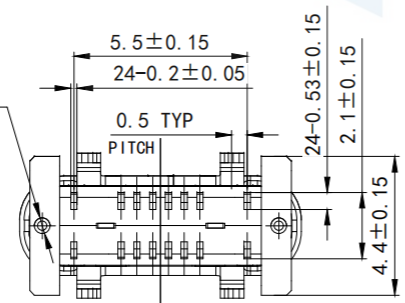
装吸取盖示意图

RECOMMENDED P.C.B. LAYOUT (T:1.00mm)
TOLERANCE UNSPECIFIED ±0.05mm

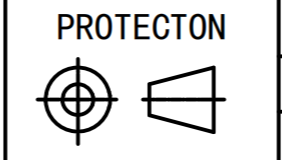



Pin NO	Signal Name	Pin NO	Signal Name
A1	GND	B12	GND
A2	SSRXP1	B11	SSRXP1
A3	SSRXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU1
A6	D+	B7	D-
A7	D-	B6	D+
A8	SBU1	B5	CC1
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSRXN2
A11	SSRXP2	B2	SSRXP2
A12	GND	B1	GND

Remark:
 1. Material:
 1.1 Core: LCP+30%G.F UL94V-0
 1.2 Terminal: high conductivity copper C7025, T=0.15mm, nickel bottom 50U" MIN.
 The contact area is gold-plated (AU 1u) and the soldering area is gold-plated G/F
 1.3 Shell: SUS304, T=0.30mm, nickel plating 50U" MIN
 1.4 Clip: SUS301, T=0.15mm;
 2. Main features:
 2.1 Rated current: 5A
 2.2 Contact Impedance: 40mΩ E MAX (initial value)
 50mΩ MAX (post-test)
 2.3 INSULATION RESISTANCE: 100MΩ E MIN
 2.4 Hipot test: 100V AC R.M.S.
 2.6 Overall insertion force: 5-20N Integral insertion force: 5-20N (after durability) Overall Pulling Force: 8-20N Overall Pulling Force: 6-20N (after durability)
 2.7 Durability: 10000 times
 2.8 High temperature resistance: SMT reflow soldering (peak 260 ° ± 5 °), plastic can not be blistered.
 Poor glue melting, discoloration, warping and deformation within the tolerance range:
 2.9 The product must be soldered tested, and the tin area should reach more than 95%;
 3.0 SALT SPRAY TEST: 48H MIN
 3.1 Working temperature: -30 ° C~+85 ° C



TOLERANCE	
X. XXX	±0.05
X. XX	±0.15
X. X	±0.20
X.	±0.30
ANGLE	±5.0°



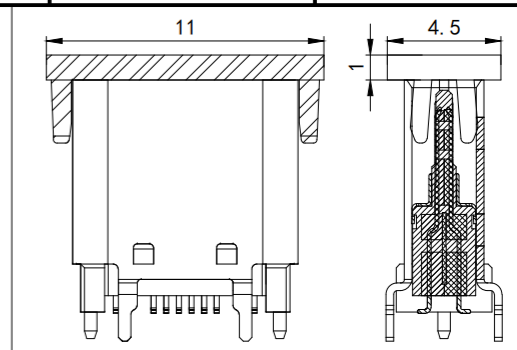
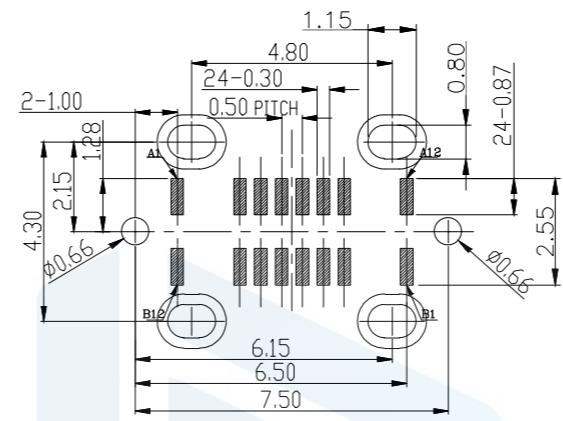
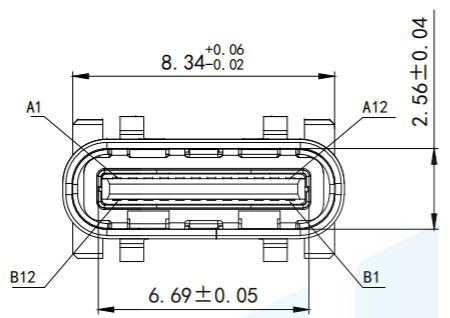


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Dongguan Hengqi Electronic Technology Co., Ltd

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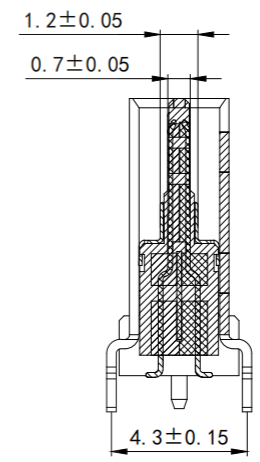
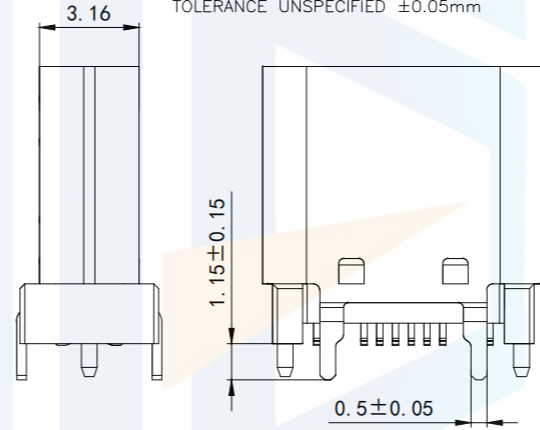
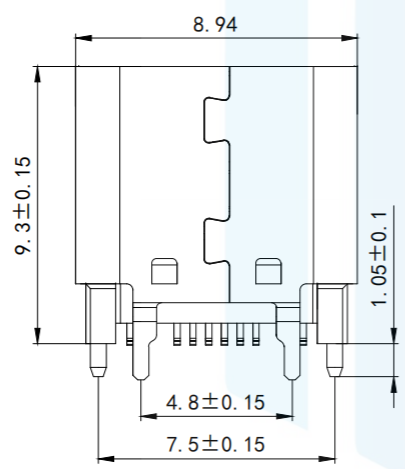
TITLE: TYPE C 16P立式贴片L=8.8		PART NO: TYPE-C16P-LT105	
		DRAWING NO: 8.94*3.16*8.8	
DRAWN:		DATE:	18-10-08
CHECKED:		DATE:	18-10-08
APPROVED:		DATE:	18-10-08
		UNIT:	mm
		SCALE:	FULL
		SIZE:	A4

RoHS2.0
Compliant



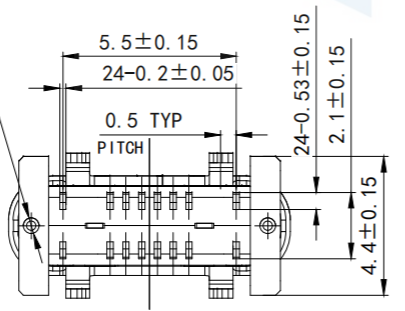
装吸取盖示意图

RECOMMENDED P.C.B. LAYOUT (T:1.00mm)
TOLERANCE UNSPECIFIED ±0.05mm



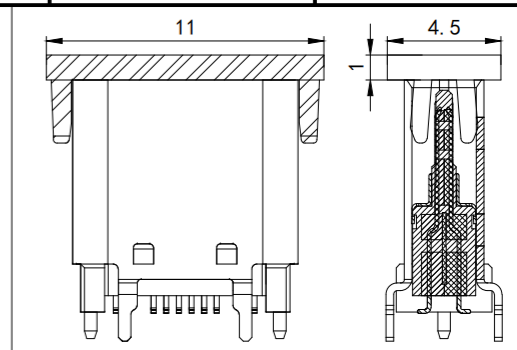
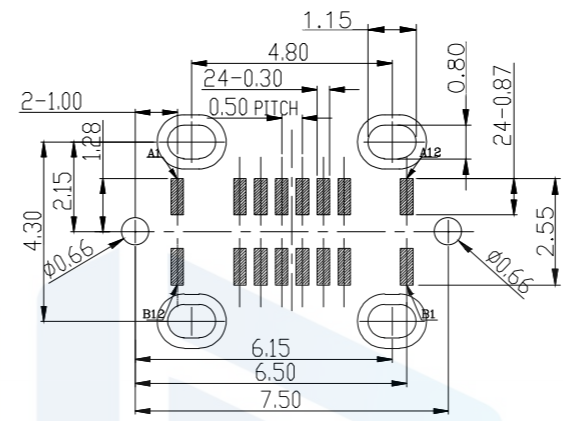
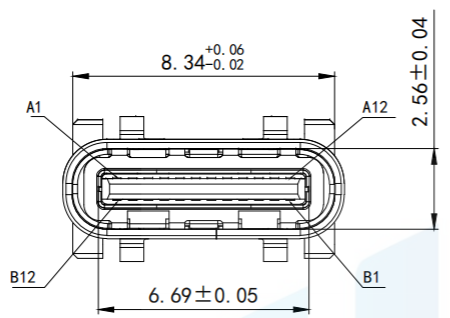
Pin NO	Signal Name	Pin NO	Signal Name
A1	GND	B12	GND
A2	SSRXP1	B11	SSRXP1
A3	SSRXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU1
A6	D+	B7	D-
A7	D-	B6	D+
A8	SBU1	B5	CC1
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSRXN2
A11	SSRXP2	B2	SSRXP2
A12	GND	B1	GND

Remark:
 1. Material:
 1.1 Core: LCP+30%G.F UL94V-0
 1.2 Terminal: high conductivity copper C7025, T=0.15mm, nickel bottom 50U" MIN.
 The contact area is gold-plated (AU 1u) and the soldering area is gold-plated G/F
 1.3 Shell: SUS304, T=0.30mm, nickel plating 50U" MIN
 1.4 Clip: SUS301, T=0.15mm;
 2. Main features:
 2.1 Rated current: 5A
 2.2 Contact Impedance: 40mΩ MAX (initial value)
 50mΩ MAX (post-test)
 2.3 INSULATION RESISTANCE: 100MΩ MIN
 2.4 Hipot test: 100V AC R.M.S.
 2.6 Overall insertion force: 5-20N Integral insertion force: 5-20N (after durability) Overall Pulling Force: 8-20N Overall Pulling Force: 6-20N (after durability)
 2.7 Durability: 10000 times
 2.8 High temperature resistance: SMT reflow soldering (peak 260 ° ± 5 °), plastic can not be blistered.
 Poor glue melting, discoloration, warping and deformation within the tolerance range:
 2.9 The product must be soldered tested, and the tin area should reach more than 95%;
 3.0 SALT SPRAY TEST: 48H MIN
 3.1 Working temperature: -30 ° C~+85 ° C



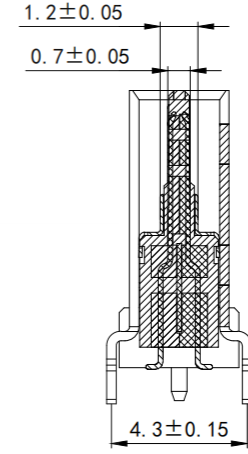
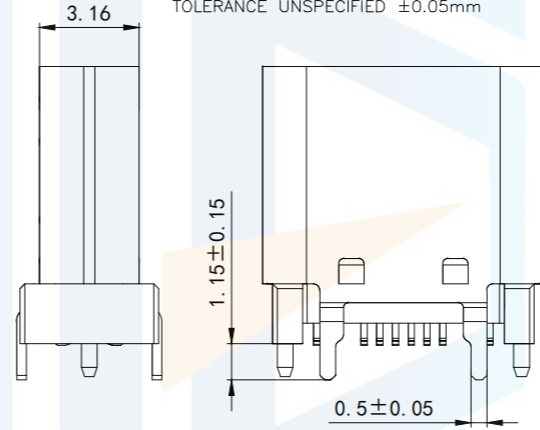
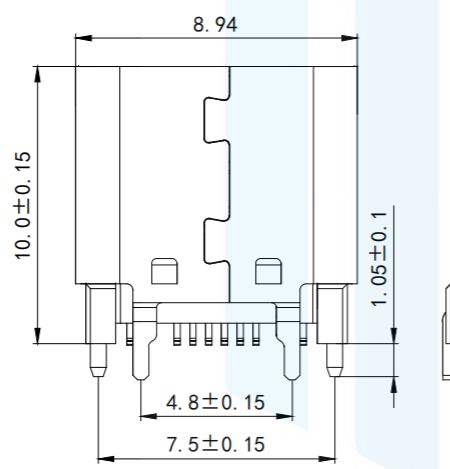
TOLERANCE X. XXX ±0.05 X. XX ±0.15 X. X ±0.20 X. ±0.30 ANGLE ±5.0°		东莞市恒祺电子科技有限公司 Dongguan Hengqi Electronic Technology Co., Ltd	
		https://www.hq-dz.com phone:15812872448	
PROTECTON 	DRAWN: CHECKED: APPROVED:	TITLE: TYPE C 16P立式贴片L=9.3	
		PART NO: TYPE-C16P-LT105	
		DRAWING NO: 8.94*3.16*9.3	
		DATE: 18-10-08	UNIT: mm
		DATE: 18-10-08	SCALE: FULL
		DATE: 18-10-08	SIZE: A4

RoHS2.0
Compliant



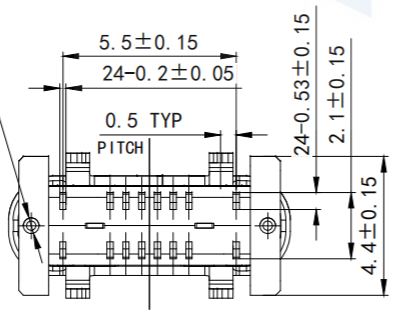
装吸取盖示意图

RECOMMENDED P.C.B. LAYOUT (T:1.00mm)
TOLERANCE UNSPECIFIED ±0.05mm

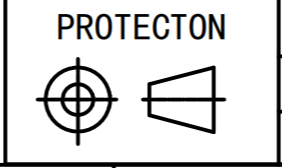



Pin NO	Signal Name	Pin NO	Signal Name
A1	GND	B12	GND
A2	SSRXP1	B11	SSRXP1
A3	SSRXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU1
A6	D+	B7	D-
A7	D-	B6	D+
A8	SBU1	B5	CC1
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSRXN2
A11	SSRXP2	B2	SSRXP2
A12	GND	B1	GND

Remark:
 1. Material:
 1.1 Core: LCP+30%G.F UL94V-0
 1.2 Terminal: high conductivity copper C7025, T=0.15mm, nickel bottom 50U" MIN.
 The contact area is gold-plated (AU 1u) and the soldering area is gold-plated G/F
 1.3 Shell: SUS304, T=0.30mm, nickel plating 50U" MIN
 1.4 Clip: SUS301, T=0.15mm;
 2. Main features:
 2.1 Rated current: 5A
 2.2 Contact Impedance: 40mΩ MAX (initial value)
 50mΩ MAX (post-test)
 2.3 INSULATION RESISTANCE: 100MΩ MIN
 2.4 Hipot test: 100V AC R.M.S.
 2.6 Overall insertion force: 5-20N Integral insertion force: 5-20N (after durability) Overall Pulling Force: 8-20N Overall Pulling Force: 6-20N (after durability)
 2.7 Durability: 10000 times
 2.8 High temperature resistance: SMT reflow soldering (peak 260 ° ± 5 °), plastic can not be blistered.
 Poor glue melting, discoloration, warping and deformation within the tolerance range;
 2.9 The product must be soldered tested, and the tin area should reach more than 95%;
 3.0 SALT SPRAY TEST: 48H MIN
 3.1 Working temperature: -30 ° C~+85 ° C

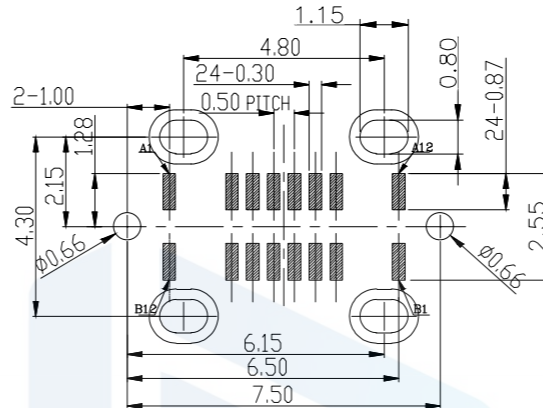
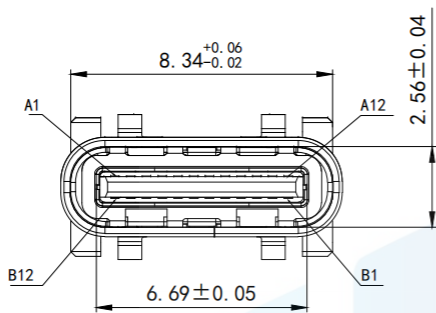


TOLERANCE	
X. XXX	±0.05
X. XX	±0.15
X. X	±0.20
X.	±0.30
ANGLE	±5.0°

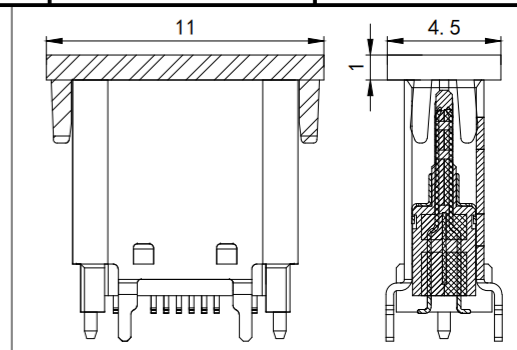


	东莞市恒祺电子科技有限公司 Dongguan Hengqi Electronic Technology Co., Ltd	
	https://www.hq-dz.com phone:15812872448	
TITLE: TYPE C 16P立式贴片L=10.0		PART NO: TYPE-C16P-LT105
DRAWN:		DATE: 18-10-08
CHECKED:		DATE: 18-10-08
APPROVED:		DATE: 18-10-08
		UNIT: mm
		SCALE: FULL
		SIZE: A4

RoHS2.0
Compliant

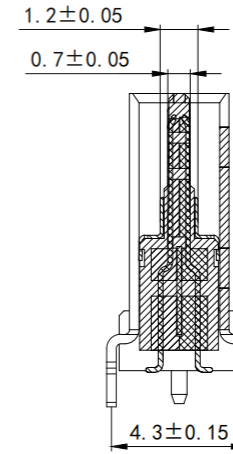
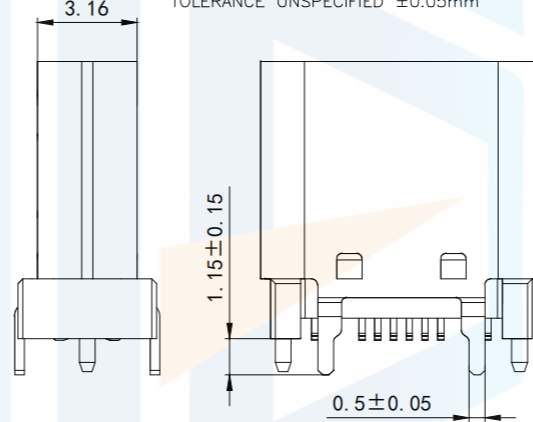
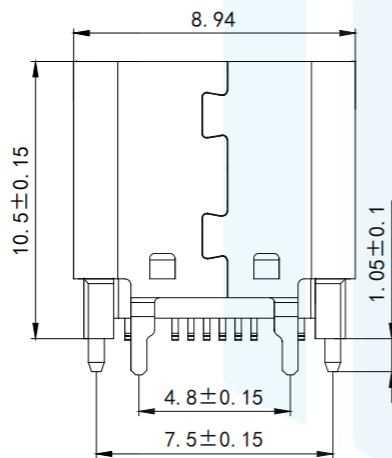


RECOMMENDED P.C.B. LAYOUT (T:1.00mm)
TOLERANCE UNSPECIFIED ±0.05mm

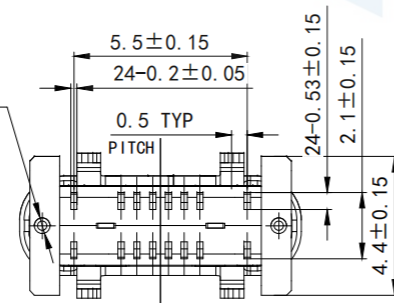


装吸取盖示意图

Pin NO	Signal Name	Pin NO	Signal Name
A1	GND	B12	GND
A2	SSRXP1	B11	SSRXP1
A3	SSRXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU1
A6	D+	B7	D-
A7	D-	B6	D+
A8	SBU1	B5	CC1
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSRXN2
A11	SSRXP2	B2	SSRXP2
A12	GND	B1	GND



Remark:
1. Material:
1.1 Core: LCP+30%G.F UL94V-0
1.2 Terminal: high conductivity copper C7025, T=0.15mm, nickel bottom 50U" MIN.
The contact area is gold-plated (AU 1u) and the soldering area is gold-plated G/F
1.3 Shell: SUS304, T=0.30mm, nickel plating 50U" MIN
1.4 Clip: SUS301, T=0.15mm;
2. Main features:
2.1 Rated current: 5A
2.2 Contact Impedance: 40mΩ MAX (initial value)
50mΩ MAX (post-test)
2.3 INSULATION RESISTANCE: 100MΩ MIN
2.4 Hipot test: 100V AC R.M.S.
2.6 Overall insertion force: 5-20N Integral insertion force: 5-20N (after durability) Overall Pulling Force: 8-20N Overall Pulling Force: 6-20N (after durability)
2.7 Durability: 10000 times
2.8 High temperature resistance: SMT reflow soldering (peak 260 ° ± 5 °), plastic can not be blistered.
Poor glue melting, discoloration, warping and deformation within the tolerance range;
2.9 The product must be soldered tested, and the tin area should reach more than 95%;
3.0 SALT SPRAY TEST: 48H MIN
3.1 Working temperature: -30 ° C~+85 ° C



TOLERANCE	X. XXX	±0.05		东莞市恒祺电子科技有限公司 Dongguan Hengqi Electronic Technology Co., Ltd		
	X. XX	±0.15		https://www.hq-dz.com phone:15812872448		
X. X ±0.20 X. ±0.30 ANGLE ±5.0°	TITLE:		PART NO:TYPE-C16P-LT105			
	TYPE C 16P立式贴片L=10.5		DRAWING NO:8.94*3.16*10.5			
	PROTECTON	DRAWN:	DATE:	18-10-08	UNIT: mm	
	CHECKED:	DATE:	18-10-08	SCALE: FULL		
	APPROVED:	DATE:	18-10-08	SIZE: A4		